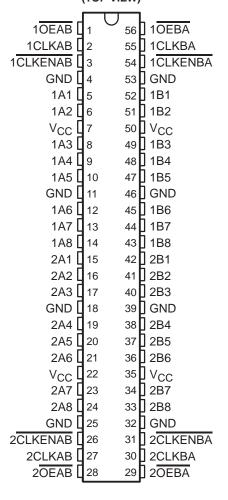
- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16952 are 16-bit registered transceivers that contain two sets of D-type flip-flops for temporary storage of data flowing in either direction. The 'ABT16952 can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

SN54ABT16952 . . . WD PACKAGE SN74ABT16952 . . . DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16952 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16952 is characterized for operation from –40°C to 85°C.



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SN54ABT16952, SN74ABT16952 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS082C - FEBRUARY 1991 - REVISED JANUARY 1997

FUNCTION TABLE†

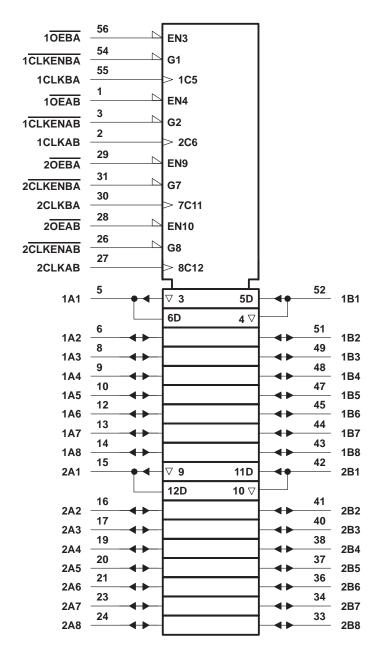
	INPUTS									
CLKENAB	CLKAB	OEAB	Α	В						
Н	Х	L	Χ	в ₀ ‡						
Х	L	L	Χ	B ₀ ‡						
L	\uparrow	L	L	L						
L	\uparrow	L	Н	Н						
Х	X	Н	Χ	Z						

[†] A-to-B data flow is shown; B-to-A data flow is similar, but uses CLKENBA, CLKBA, and OEBA.



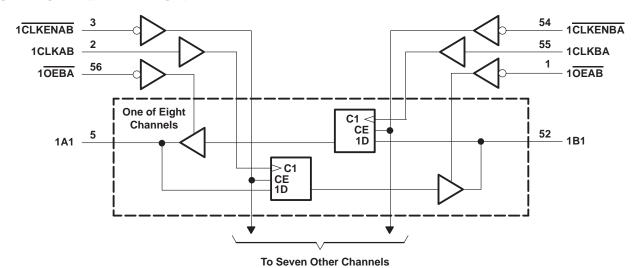
[‡]Level of B before the indicated steady-state input conditions were established

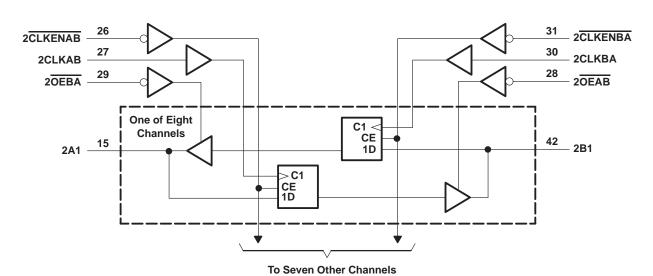
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)







absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, VI (except I/O po	rts) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output ir	the high or power-off state, V_O .	–0.5 V to 5.5 V
Current into any output in the low stat	e, I _O : SN54ABT16952	96 mA
	SN74ABT16952	128 mA
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I_{OK} ($V_O < 0$).		–50 mA
Package thermal impedance, θ _{JA} (see	e Note 2): DGG package	81°C/W
	DL package	74°C/W
Storage temperature range, T _{stq}		–65°C to 150°C
o i oig		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54ABT	16952	SN74AB1	16952	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage	2	EM	2		V	
V _{IL}	V _{IL} Low-level input voltage					0.8	V
VI	Input voltage		0 0	Vcc	0	VCC	V
ІОН	High-level output current		(2)	-24		-32	mA
loL	Low-level output current	200	48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	72	10		10	ns/V
TA	Operating free-air temperature		– 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SN54ABT16952, SN74ABT16952 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS082C - FEBRUARY 1991 - REVISED JANUARY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAF	DAMETER	TEST COL	NOTIONS	Т	A = 25°C	;	SN54AB	Г16952	SN74AB1	16952	UNIT	
PAR	RAMETER	TEST COI	SNOTTIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V}, \qquad I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/~		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				v	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
\/01		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100			2			mV	
١.	Control inputs	V00 - 5 5 V	V _I = V _{CC} or GND			±1		<u>/</u> ±1		±1	μА	
l _l	A or B ports	V _{CC} = 5.5 V,	AL = ACC OL GIAD			±100		±100		±100	μΛ	
lozh‡		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50	9	50		50	μΑ	
I _{OZL} ‡		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			- 50	5	- 50		-50	μΑ	
I _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	90			±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	Q	50		50	μА	
I _O §		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-200	-50	-200	-50	-200	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
Icc	A or B ports	$I_{O} = 0$,	Outputs low			35		35		35	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		2		2		2			
ΔICC¶		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				0.5		0.5		0.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3						pF	
Cio	A or B ports	V _O = 2.5 V or 0.5 V	/		8.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

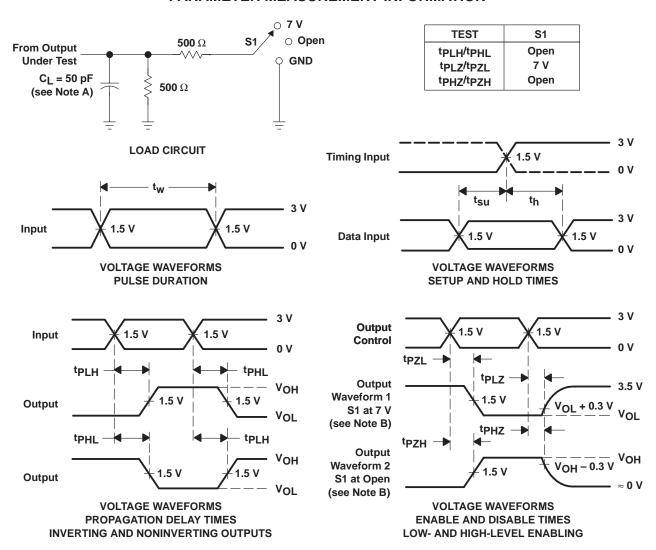
			V _{CC} =	= 5 V, 25°C	SN54AB	Г16952	SN74AB1	T16952	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	0	150	MHz	
t _W †	Pulse duration, CLKAB or CLKBA h	3.3		3.3	7	3.3		ns	
	Setup time,	A or B	3.5		3.5		3.5		20
^l su	t _{su} before CLKAB↑ or CLKBA↑	CLKENAB or CLKENBA	3		3		3		ns
ţ.	Hold time,	A or B	1		0 1		1		ne
^t h	after CLKAB↑ or CLKBA↑	CLKENAB or CLKENBA	1		Q 1		1	·	ns

[†] This parameter is warranted, but not production tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT16952		SN74ABT16952		UNIT
	(INFOT)	(0011-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150			150	N	150		MHz
^t PLH	CLK	A or B	1	2.6	3.9	1	4.4	1	4.3	ns
^t PHL	CLK		1	2.6	4.2	1,0	4.6	1	4.5	115
^t PZH	ŌĒ	A or B	1	2.5	3.8	1	4.7	1	4.6	ns
t _{PZL}	OE	A OF B	1	2.8	5.1	25	6.1	1	6	115
^t PHZ	ŌĒ	A or B	1.7	3.4	4.7	O _{1.7}	6.1	1.7	5.5	ns
t _{PLZ}	OE	AUIB	1.3	3	3.9	1.3	4.8	1.3	4.2	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABT16952DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16952DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16952DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16952DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16952DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16952DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16952DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

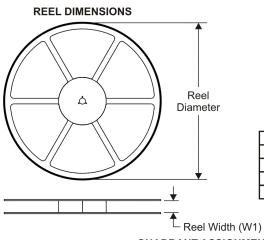
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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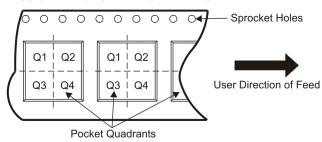
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

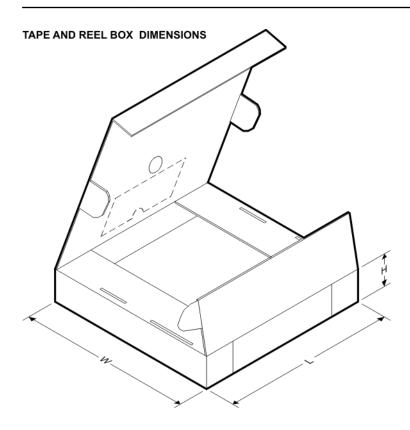
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16952DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16952DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16952DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ABT16952DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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